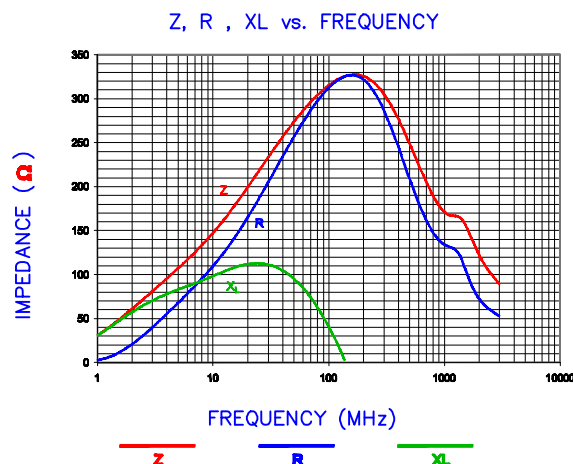
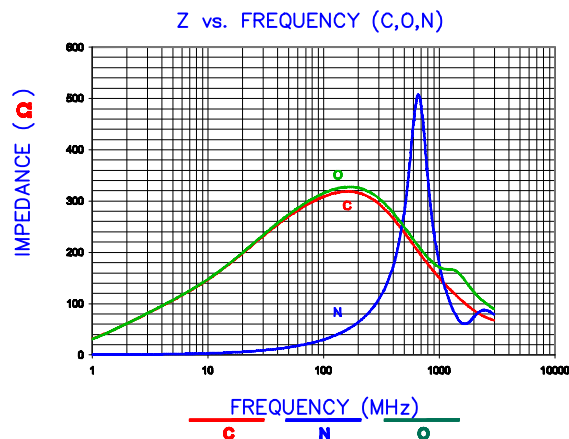
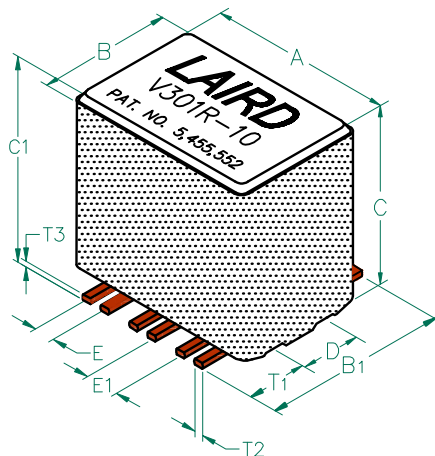


A	11.94	[.470]	$\uparrow$	0.18	[.007]
B	8.13	[.320]	$\downarrow$	0.13	[.005]
B ₁	10.92	[.430]		MAX	
C	14.48	[.570]	$\uparrow$	0.25	[.010]
C ₁	15.11	[.595]		MAX	
D	4.06	[.160]	$\uparrow$	0.05	[.002]
E	1.27	[.050]	$\downarrow$	0.13	[.005]
E ₁	2.03	[.080]	$\uparrow$	0.13	[.005]

T_1	3.30 [.130]	$+ 0.38$ [.015]
T_2	0.64 [.025]	TYP
T_3	0.38 [.015]	TYP



CM4732V301R-10



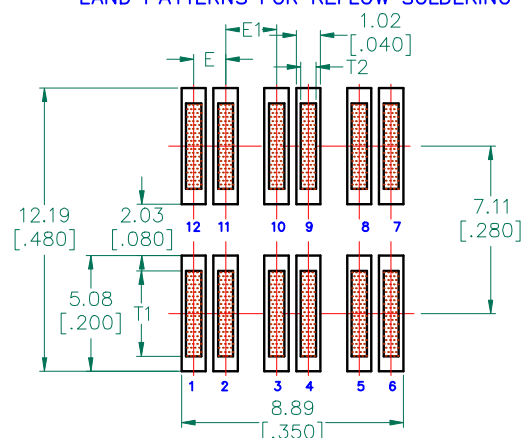
**UNCONTROLLED
DOCUMENT**



Z @ 100MHz (Ω)		DCR (Ω)	Rated Current
Nominal	300		
Minimum	225		
Maximum	375	0.01	8,000 mA

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 150 PCS/REEL.
2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
3. REF. CARRIER TAPE SPECIFICATION #CART4732-33.
4. TERMINATION FINISH IS 100% TIN.
5. THIS PART HAS NO PIN POLARITY.

LAND PATTERNS FOR REFLOW SOLDERING



The graph illustrates the temperature profile of a soldering process. The y-axis represents Temperature in degrees Celsius (°C) and degrees Fahrenheit (°F). The x-axis represents time in seconds. The profile is divided into three phases: Pre-Heating, Soldering, and Natural Cooling.

Phase	Duration (Seconds)	Temperature (°C)	Temperature (°F)
Pre-Heating	100	130	266
Soldering	60	250	482
Natural Cooling	60	250	482

DIMENSIONS ARE IN mm (INCHES).				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved. 			
C	UPDATE COMPANY LOGO and KAPTON LABEL ADD EQUIV. CIRCUIT	11/11/08	JRK	PROJECT/PART NUMBER: CM4732V301R-10	REV C	PART TYPE: ASSEMBLY	DRAWN BY: JRK
B	UPDATE COMPANY LOGO	12/12/07	JRK	DATE: 06/03/04	SCALE: NTS	SHEET:	2 of 3
A	ORIGINAL DRAFT	06/03/04	JRK	CAD # CM4732V301R-10-C-2	TOOL # H0470-3		
REV	DESCRIPTION	DATE	INT				